



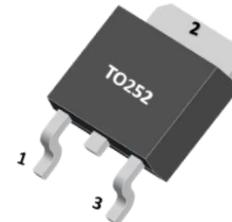
# HY20N10

N-CHANNEL POWER MOSFET

## 20A, 100V N-CHANNEL ENHANCEMENT MODE POWER MOSFET

### ■ DESCRIPTION

The XD20N10Y is a high voltage power MOSFET and is designed to have better characteristics, such as fast switching time, low gate charge, low on-state resistance and have a high rugged avalanche characteristics. This power MOSFET is usually used at high speed switching applications in power supplies, PWM motor controls, high efficient DC to DC converters and bridge circuits.



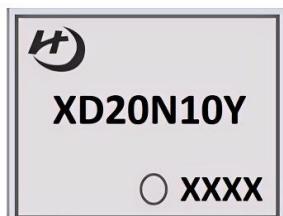
### ■ FEATURE

- \* RDS(ON) ≤ 50 mΩ @ VGS=10V, ID=10A

- \* High switching speed

- \* 100% avalanche tested

### ■ MARKING



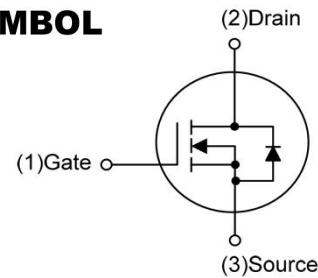
: HY LOGO

XD20N10Y=Device Code

XXXX=Date Code

Solid Dot=Green molding compound

### ■ SYMBOL



### ■ ABSOLUTE MAXIMUM RATINGS(TA=25°C, unless otherwise specified.)

SYMBOL	PARAMETER	VALUE	UNIT	
V <sub>DSS</sub>	Drain-Source Voltage	100	V	
V <sub>GSS</sub>	Gate Source Voltage	±20	V	
I <sub>D</sub>	Continuous Drain Current	20	A	
I <sub>DM</sub>	Pulsed Drain Current	60	A	
E <sub>A</sub>	Single Pulsed Avalanche Energy	275	mJ	
dV/dt	Peak Diode Recovery dV/dt (Note 4)	5.03	V/ns	
P <sub>D</sub>	Maximum Power Dissipation (Note 1)	TO-252	58	W
T <sub>J</sub>	Storage Temperature	150	°C	
T <sub>STG</sub>	Thermal Resistance Fr .00m Junction To Ambient	-55~150	°C	
R <sub>θJA</sub>	Thermal Resistance from Junction to Ambient (Note 5)	TO-252	110	°C/W
R <sub>θJC</sub>	Thermal Resistance From Junction To Case	TO-252	2.15	°C/W

Notes: 1. Absolute maximum ratings are those values beyond which the device could be permanently damaged.

Absolute maximum ratings are stress ratings only and functional device operation is not implied.

2. Repetitive Rating: Pulse width limited by maximum junction temperature.

3. L=1.0mH, IAS=23A, VDD=50V, RG=25 Ω, Starting TJ = 25°C

4. ISD ≤ 20A, di/dt ≤ 200A/μs, VDD ≤ BV<sub>DSS</sub>, Starting TJ = 25°C

5. Device mounted on FR-4 substrate PC board, 2oz copper, with 1inch square copper plate.



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■ ELECTRICAL CHARACTERISTICS (TA=25°C, unless otherwise specified)

PARAMETER	SYMBOL	TEST CONDITIONS	MIN	TYP	MAX	UNIT
<b>OFF CHARACTERISTICS</b>						
Drain-Source Breakdown Voltage	V <sub>(BR)DSS</sub>	V <sub>GS</sub> =0V, I <sub>D</sub> =250μA	100			V
Zero gate voltage drain current	I <sub>DSS</sub>	V <sub>DS</sub> =48V, V <sub>GS</sub> =0V			1	μA
Gate-body leakage current	I <sub>GSS</sub>	V <sub>GS</sub> =±20V, V <sub>DS</sub> =0V			±100	nA
<b>ON CHARACTERISTICS</b>						
Drain-source on-state resistance	R <sub>DSON</sub>	V <sub>GS</sub> =10V, I <sub>D</sub> =10A			50	mΩ
Gate Threshold Voltage	V <sub>GS(TH)</sub>	V <sub>GS</sub> =V <sub>DS</sub> , I <sub>D</sub> =250μA	2.0		4.0	V
<b>DYNAMIC PARAMETERS</b>						
Input Capacitance	C <sub>ISS</sub>	V <sub>GS</sub> =0V, V <sub>DS</sub> =25V f=1.0MHz		1840		pF
Output Capacitance	C <sub>OSS</sub>			245		
Reverse Transfer Capacitance	C <sub>rss</sub>			20		
<b>SWITCHING PARAMETER</b>						
Total gate charge (Note 1)	Q <sub>G</sub>	V <sub>DS</sub> =80V, V <sub>GS</sub> =10V I <sub>D</sub> =20A, I <sub>G</sub> =1mA (Note 1, 2)		42		nC
Gate-source charge	Q <sub>GS</sub>			14		
Gate-drain charge	Q <sub>GD</sub>			7		
Turn-On Delay Time (Note 1)	t <sub>d(on)</sub>	V <sub>DD</sub> =50V, I <sub>D</sub> =20A V <sub>GS</sub> =10V, R <sub>G</sub> =25Ω (Note 1, 2)		20		nS
Turn-On Rise time	t <sub>r</sub>			20.5		
Turn-Off Delay Time	t <sub>d(off)</sub>			100		
Turn-Off Fall time	t <sub>f</sub>			23		
<b>DRAIN-SOURCE DIODE CHARACTERISTICS AND MAXIMUM RATINGS</b>						
Continuous drain-source diode forward current	I <sub>S</sub>				20	A
Pulsed drain-source diode forward current	I <sub>SM</sub>				60	A
Drain-source diode forward voltage (Note 1)	V <sub>SD</sub>	I <sub>S</sub> =10A, V <sub>GS</sub> =0V			1.4	V
Body Diode Reverse Recovery Time (Note 1)	t <sub>rr</sub>	I <sub>S</sub> =20A, V <sub>GS</sub> =0V dI/dt = 100A/μs		80		ns
Body Diode Reverse Recovery Charge	Q <sub>rr</sub>			0.56		μC

Notes:

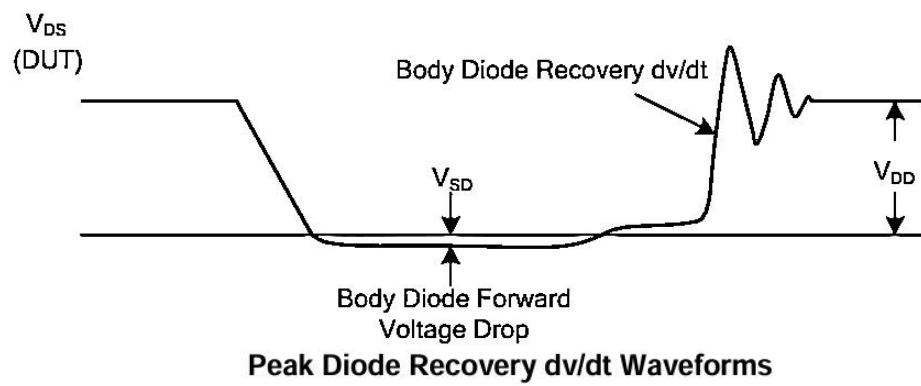
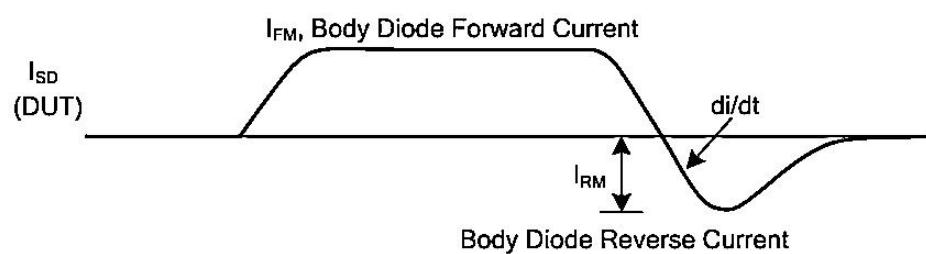
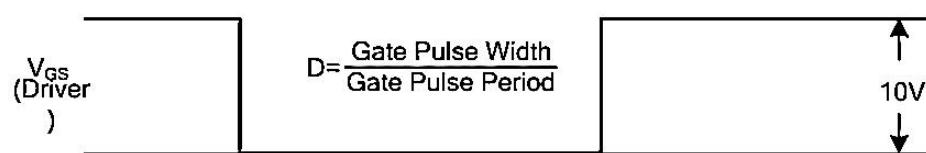
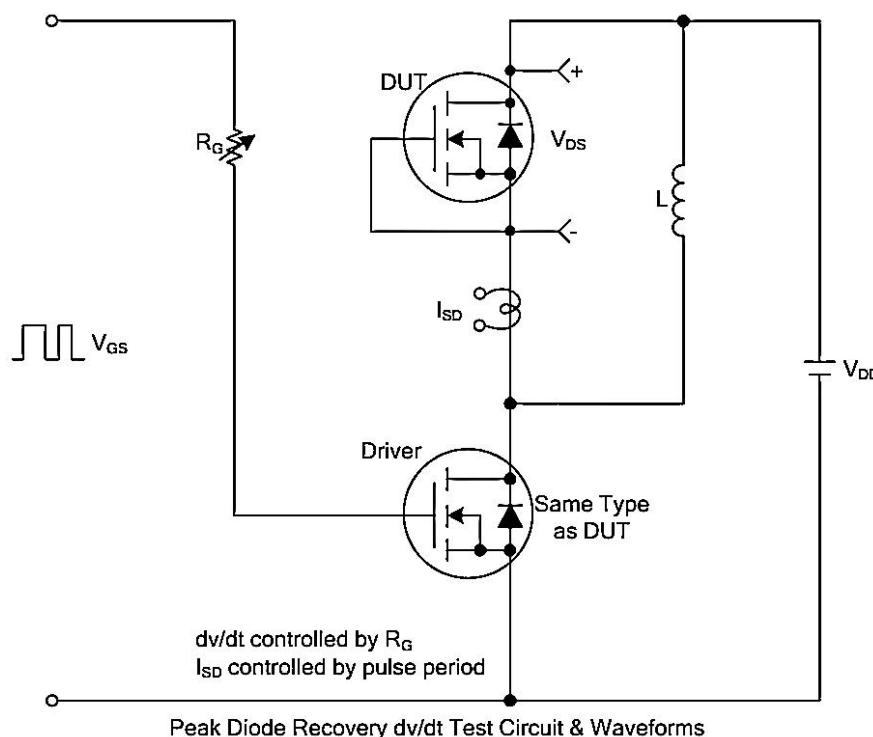
1. Pulse Test : Pulse Width≤300μs, duty cycle ≤2%.
2. Essentially independent of operating temperature.



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■ TEST CIRCUITS AND WAVEFORMS(1)

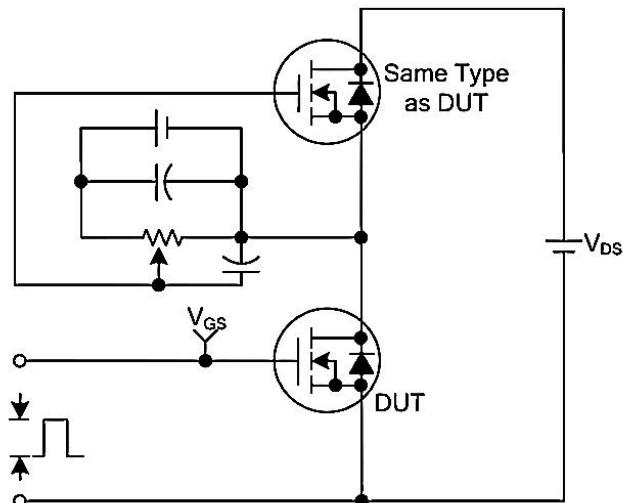




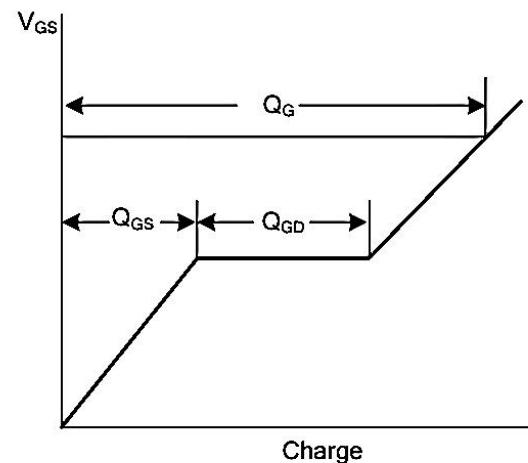
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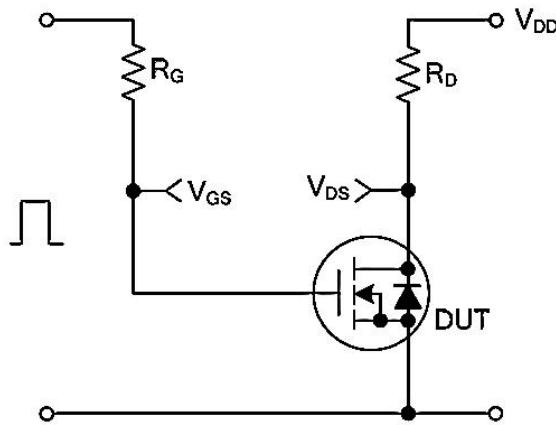
■ TEST CIRCUITS AND WAVEFORMS(2)



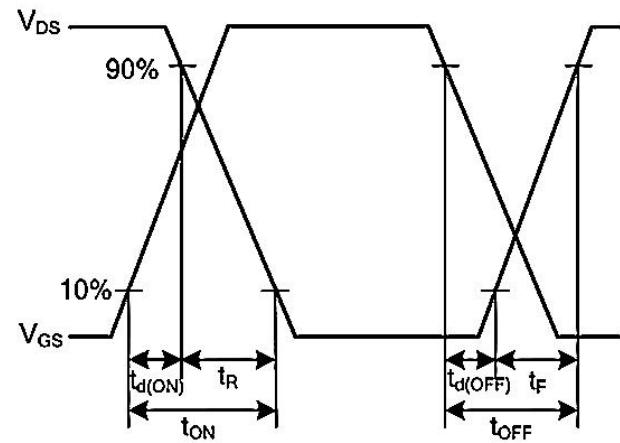
Gate Charge Test Circuit



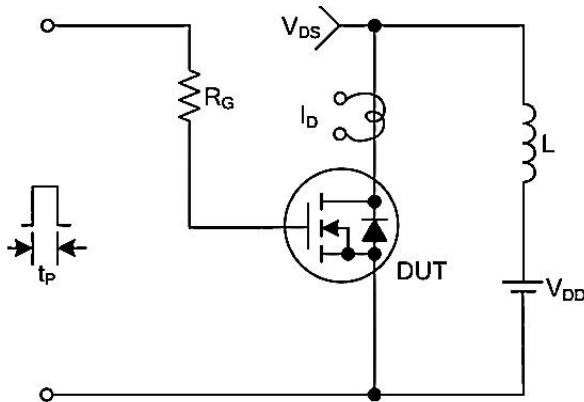
Gate Charge Waveforms



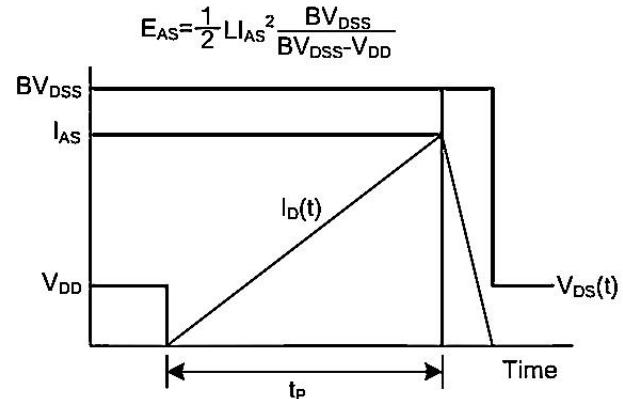
Resistive Switching Test Circuit



Resistive Switching Waveforms



Unclamped Inductive Switching Test Circuit



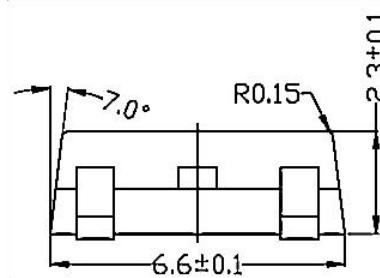
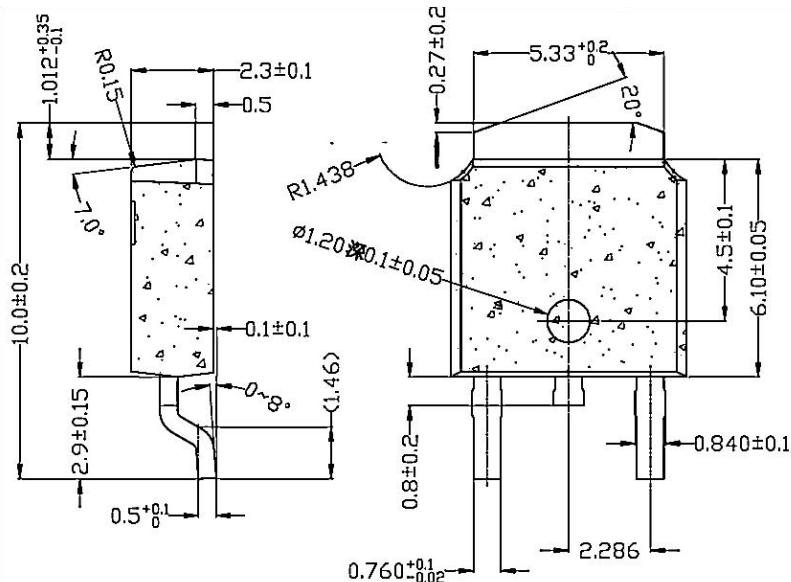
Unclamped Inductive Switching Waveforms



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## **N-CHANNEL POWER MOSFET**

## ■ TO - 252 PACKAGE OUTLINE DIMENSIONS



## ■ TO - 252 PACKING INFORMATION



Package version	Reel dimensions $\Phi \times H$ (mm)	Per Reel (pcs)	Reels per box	Inner box dimensions L×W×H (mm)	Outer box (pcs)	Outer box dimensions L×W×H (mm)
T0-252	$\Phi 330 \times 20$	2500	2	360*340*50	25000	375*375*280